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合生創展集團有限公司*

HOPSON DEVELOPMENT HOLDINGS LIMITED

(Incorporated in Bermuda with limited liability)

(Stock Code: 754)

website: http://www.irasia.com/listco/hk/hopson

SUPPLEMENTAL ANNOUNCEMENT IN RELATION TO THE PROPOSED ISSUE OF US$250,000,000 8.00% GUARANTEED CONVERTIBLE BONDS

Reference is made to the announcement of the Company dated 9 December 2021, the supplemental announcement of the Company dated 16 December 2021 (the "**First Supplemental Announcement**") and the circular of the Company dated 17 December 2021 (the "**Circular**") each in relation to, *inter alia*, the proposed issue of US$250,000,000 8.00% guaranteed convertible bonds. Unless otherwise defined, capitalised terms used in this announcement shall have the same meanings given to them in the Circular.

UPDATED BOND CLOSING DATE AND ISSUE DATE OF THE BONDS

In the First Supplemental Announcement, the Bond Closing Date and the Issue Date are referred to as "unless an earlier Bond Closing Date is announced by the Company, 14 January 2022, or such later date as the Company, the Subsidiary Guarantors and the Sole Bookrunner and the Sole Lead Manager may agree" and "unless an earlier Issue Date is announced by the Company, 14 January 2022, or such later date as the Company, the Subsidiary Guarantors and the Sole Bookrunner and the Sole Lead

Manager may agree", respectively. The Board hereby announces that, subject to the satisfaction and/or waiver of the conditions precedent set out in the Subscription Agreement, the Bond Closing Date and the Issue Date of the Bonds will take place on 10 January 2022.

Save for the above, all other terms and conditions of the Subscription Agreement as disclosed in the Announcements and the Circular shall remain in full force and effect.

Completion of the Subscription Agreement is subject to the satisfaction and/or waiver of the conditions precedent therein. In addition, the Subscription Agreement may be terminated in certain circumstances. As the Bond Issue may or may not complete, Shareholders and potential investors are advised to exercise caution when dealing in the securities of the Company.

By Order of the Board
Hopson Development Holdings Limited
Chu Kut Yung
Chairman

Hong Kong, 6 January 2022

As at the date of this announcement, the Board comprises eight Directors. The executive Directors are Ms. Chu Kut Yung (Chairman), Mr. Zhang Fan (Co-president), Mr. Au Wai Kin, Mr. Xie Bao Xin and Mr. Bao Wenge; and the independent non-executive Directors are Mr. Tan Leng Cheng, Aaron, Mr. Ching Yu Lung and Mr. Ip Wai Lun, William.

* *For identification purposes only*